



Material Declaration Data Sheet

Model: **Product Server Chassis S3420, SR1630GP, SC5650UP**

Manufacturer: Intel Corporation

Note: This declaration applies to all associated product codes noted on Page 2

Lead Free (Pb) Product: **Yes, for SLI, except for FSR1530BPSATA**

Date: August 24, 2009

Restriction on Hazardous Substances (RoHS) Compliance

RoHS Definition

- Quantity limit of 0.1% by mass (1000PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
- Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in the RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

RoHS Declaration

- 1** Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
- 2** Lead as an alloying element in steel containing up to 0.35 % lead by weight.
- 3** Lead as an alloying element in aluminum containing up to 0.4 % lead by weight.
- 4** Lead as an alloying element in copper containing up to 4 % lead by weight.
- 5** Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead)
- 6** Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
- 7** Lead in electronic ceramic parts (e.g. piezoelectronic devices).
- 8** Lead used in compliant pin connector systems.
- 9** Lead as a coating material for the thermal conduction module c-ring.
- 10** Lead in optical and filter glass.
- 11** Lead in solders consisting of more than two parts for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
- 12** Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
- 13** Cadmium in optical and filter glass.
- 14** Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
- 15** Lead in bronze bearing shells and brushes.
- 16** Lead in printing inks for application of enamels on borosilicate glass
- 17** Cadmium in printing inks for application of enamels on borosilicate glass
- 18** Lead in Finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with NiFe lead frames and and lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with copper lead frames
- 19** Lead in solders for the soldering to machined through hole discoidal and planar array ceramic capacitors
- 20** Lead oxide in plasma display panels (PDP) and surface conduction electron emitter displays (SED) used in structural elements: notably in the front and rear glass dielectric layer, the bus electrode, the black stripe, the address electrode, the barrier ribs, the seal frit, and frit ring as well as in print pastes.
- 21** Other

Where the product is declared to meet RoHS requirements, it has been verified to be in conformance with 2002/95/EC as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

INTEL ACCEPTS NO DUTY TO UPDATE THIS DECLARATION OR TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION. INTEL SHALL NOT BE LIABLE FOR ANY DAMAGES, DIRECT OR INDIRECT, CONSEQUENTIAL OR OTHERWISE, SUFFERED BY USERS OR THIRD PARTIES AS A RESULT OF THE USERS RELIANCE ON INFORMATION IN THIS DECLARATION THAT HAS BEEN UPDATED OR CHANGED.

Product Code Information



Product Code	Description	*RoHS Exemption #
S3420GPLX	Server Board PCI, PCIe, PCI-X, 6 SATA , Dual GbE, SAS Module Support	2
S3420GPLC	Server Board PCI, PCIe, PCI-X, 6 SATA , Dual GbE	2
BB3420GPLC	Bulk 10 pack for S3420GPLC	2
AXXTIO	IO Shield	Complies without exemptions
SC5650UP	Server Chassis, 400W PSU and 2 fans included	1,2,3,4,5,7
SC5650UPNA	North american version of SC5650UP	1,2,3,4,5,7
AXX6DRV3GEXP	6-drive hot-swap expander SATA/SAS backplane	Compliant without exemptions
AXX6DRV3GR	6-drive hot-swap non-expanded SATA/SAS backplane	Compliant without exemptions
AXXRMM3	Remote Management Module	1
APPTHSDBKIT	Hot-swap cooling/mounting kit for SC5650	Compliant without exemptions
APP3RACKIT	Rack conversion kit for SC5650	Compliant without exemptions
APP3STDBEZEL	Spare bezel w/door for SC5650	Compliant without exemptions
FPPTUPPMKIT	Preventative Maintenance Kit for SC5650UP	Compliant without exemptions
FXXPPTFPBRD	Front Panel Board, SC5650	1,7
FXXIPMBCBL	IPMB Cables	Compliant without exemptions
FXXSESCBL	SES Cables	Compliant without exemptions
FXXSGPIOCBL	SGPIO Cables	Compliant without exemptions
AXXRJ45DB92	DSD, DCD Converter Dongles, Serial Cable (not for SC5600,SC5650)	Compliant without exemptions
FXX6DRV3GRBRD	6-drive non expanded backplane	Compliant without exemptions
FXX6DRV3GEXPBRD	6-drive expanded backplane	Compliant without exemptions
FXX10DVCARBLK	10-pack hot-swap drive carriers, black baffles	Compliant without exemptions
FPWRCABLENA	North America power cable for SC5600, SC5650 family	Compliant without exemptions
FXX400PSU	400W Power Supply, SC5650UP	1,2,3,4,5,7
SR1630GP	1U Server System, 350W PSU, 2 HD slots	1,2,3,4,5,7
SR1630HGP	1U Server System, 350W PSU, 3 hot swap carriers	1,2,3,4,5,7
SR1630GPNA	1U Server System, SR1630GP, North America version	1,2,3,4,5,7
SR1630HGPNNA	1U Server System, SR1630HGP, North America version	1,2,3,4,5,7
AHJBEZBLACK	SR1630GP Black Bezel for fixed SKU	2
ADWBEZBLACK	SR1630GP Black Bezel for hotswap SKU	2
AXXBRACKETS	Fixed mount bracket kit	Compliant without exemptions
AXXHERAIL	Tool-less slide rail kit	Compliant without exemptions
AXXSATADVDRDROM	SATA slim-line DVD	Compliant without exemptions
AXXSATADVDRWROM	SATA slim-line DVD re-writeable	Compliant without exemptions
AHJTPCRISER	HJ-T 1U half-length PCIe2 x8 riser, 5 pack	1
FHJ350WPS	350W PSU for SR1630GP/SR1630HGP	1,2,3,4,5,7
FHJTBLOWER	SR1630GP/SR1630HGP blower spare kit	4,7
FSR1530BPSATA	SATA/SAS backplane for SR1630HGP	6
FHJTUPPMKIT	Preventative Maintenance Kit, SR1630GP	Compliant without exemptions
SR1630GPSPP	GP Server, Silver PreProduction	1,2,3,4,5,7
SR1630HGSPSP	HGP Server, Silver Preproduction	1,2,3,4,5,7
SC5650UPSPP	SC5650UP Server, Silver PreProduction	1,2,3,4,5,7
SC5650UP	SC5650UP Server, Production	1,2,3,4,5,7
SC5650UPNA	SC5650UP Server, North American version	1,2,3,4,5,7
SE33523	Riser Card	Compliant without exemptions

* RoHS Exemption # corresponds with exemption #'s found on page 1.